IXYS
INTEGRATED CIRCUITS DIVISION



CPC1984Y
600V, 1A, Normally Open SIP Power Relay

Parameter	Rating	Units
Blocking Voltage	600	V_P
Load Current	1	A_{rms} / A_{DC}
On-Resistance (max)	0.66	Ω
Input / Output Isolation	4000	V_{rms}

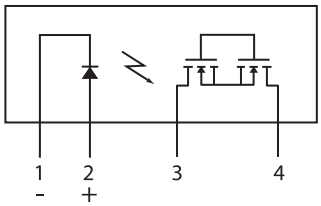
Features

- $1A_{DC}/1A_{rms}$ Load Current
- $600V_P$ Blocking Voltage
- $4000V_{rms}$ Input/Output Isolation
- Power SIP Package
- High Reliability
- Low Drive Power Requirements
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation

Applications

- Industrial Controls
- Motor Control
- Robotics
- Medical Equipment—Patient/Equipment Isolation
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- IC Equipment
- Home Appliances

Pin Configuration



Description

The CPC1984Y single-pole normally open (1-Form-A) 600V Solid State Power Relay has a $1A_{DC}$ / $1A_{rms}$ continuous load current rating.

Patented OptoMOS® optically coupled MOSFET technology, controlled by a highly efficient infrared LED, provides the CPC1984Y with $4000V_{rms}$ of input to output isolation.

The combination of low on-resistance and high load current handling capability makes this relay ideal for a variety of high performance switching applications.

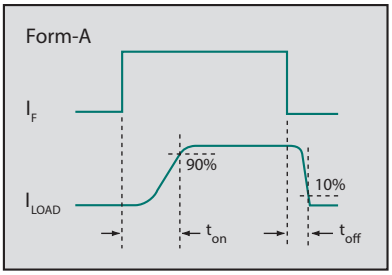
Approvals

- UL 508 Recognized Component: File E69938
- EN IEC 62368-1: TUV Certificate B 082667 0008

Ordering Information

Part #	Description
CPC1984Y	4-Pin (8-Pin Body) Power SIP Package (25 per tube)

Switching Characteristics of Normally Open Devices



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Absolute Maximum Ratings @ 25ºC

Parameter	Ratings	Units
Blocking Voltage	600	V_P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation [1]	150	mW
Total Power Dissipation [2]	1600	mW
Isolation Voltage, Input to Output (60 Seconds Maximum) [3]	4000	V_{rms}
ESD Rating, Human Body Model	4	kV
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

[1] Derate linearly 1.33mW/ºC
[2] Derate linearly 16mW/ºC
[3] UL File 69938 is rated to 2500V_{rms} by UL.

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

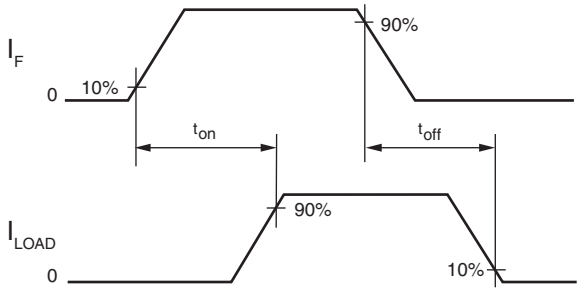
Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25ºC (Unless Otherwise Noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current, Continuous [1]	I_F=5mA, Free air	I_L	-	-	1	A
Load Current, Peak	I_F=5mA, t=10ms	I_{LPK}	-	-	5	A_P
On-Resistance [2]	I_F=5mA, I_L=1A	R_{ON}	-	0.51	0.66	Ω
Off-State Leakage Current	I_F=0mA, V_L=600V_P	I_{LEAK}	-	-	1	µA
Switching Speeds						
Turn-On	I_F=5mA, I_L=1A	t_{on}	-	2.26	10	ms
Turn-Off		t_{off}	-	0.35	2	
Output Capacitance	I_F=0mA, V=20V_{DC}, f=1MHz	C_{OUT}	-	1.18	-	nF
Input Characteristics						
Input Control Current to Activate [3]	I_L=1A	I_F	-	0.47	5	mA
Input Control Current to Deactivate	-	I_F	0.1	-	-	mA
Input Voltage Drop	I_F=5mA	V_F	0.9	1.36	1.5	V
Reverse Input Current	V_R=5V	I_R	-	-	10	µA
Input/Output Characteristics						
Capacitance, Input-to-Output	V_{IO}=0V_{DC}, f=1MHz	C_{IO}	-	2	-	pF

[1] Load derates linearly from 1000mA @ 25ºC to 650mA @ 85ºC (5.83mA/ºC).
[2] Measurement taken within 1 second of on-time.
[3] For applications requiring high temperature operation (>60°C) a minimum LED drive current of 10mA is recommended.

Switching Waveforms



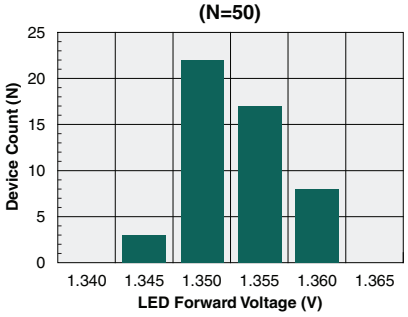
Thermal Characteristics

Parameter	Symbol	Rating
Thermal Impedance (Junction to Ambient)	θ_{JA}	62.5°C/W

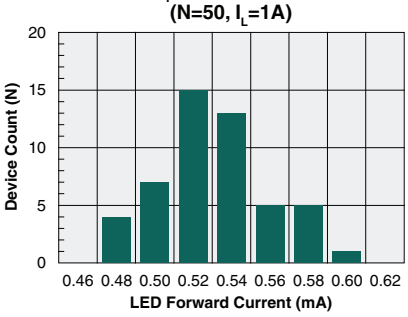
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PERFORMANCE DATA*

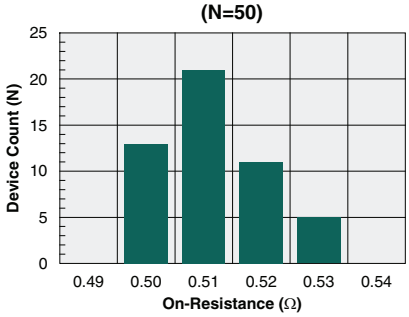
Typical LED Forward Voltage Drop (N=50)



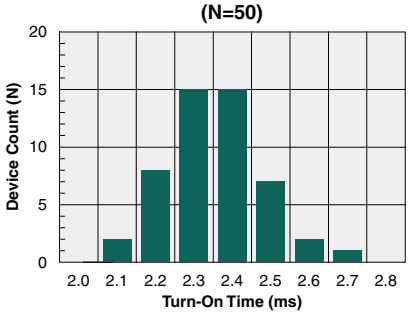
Typical I_F for Switch Operation (N=50, I_L=1A)



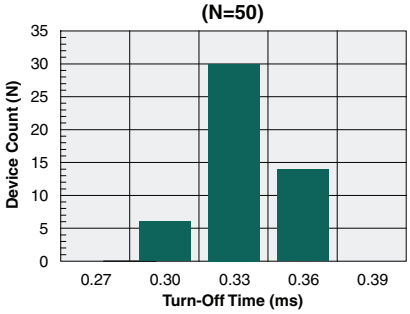
Typical On-Resistance Distribution (N=50)



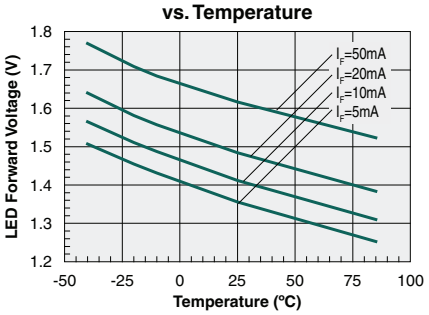
Typical Turn-On Time Distribution (N=50)



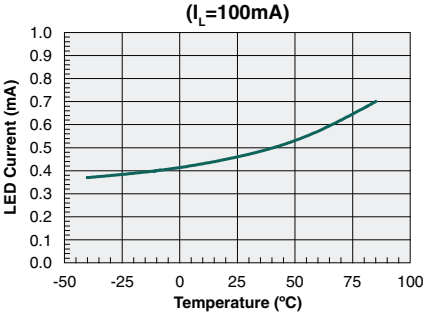
Typical Turn-Off Time Distribution (N=50)



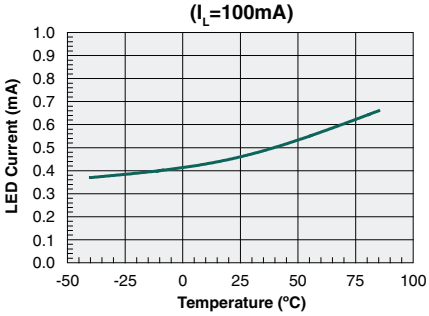
LED Forward Voltage Drop vs. Temperature



Typical I_F for Switch Operation vs. Temperature (I_L=100mA)



Typical I_F for Switch Dropout vs. Temperature (I_L=100mA)

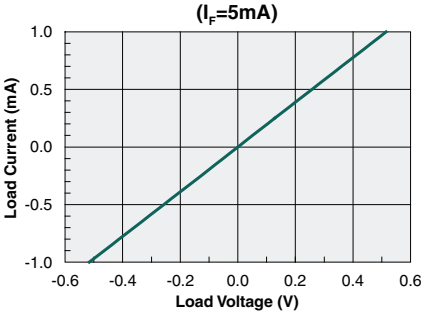


*The Performance data shown in the graphs above is typical of device operation. Unless otherwise noted, data is presented at 25°C.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

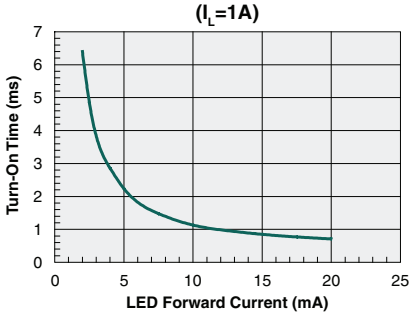
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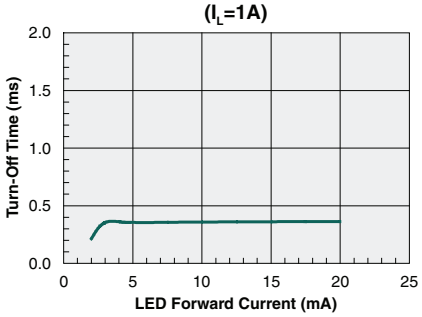
Typical Load Current vs. Load Voltage (I_F=5mA)



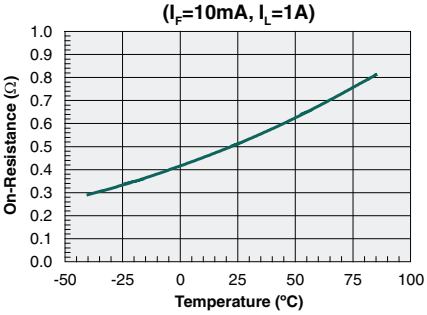
Typical Turn-On Time vs. LED Forward Current (I_L=1A)



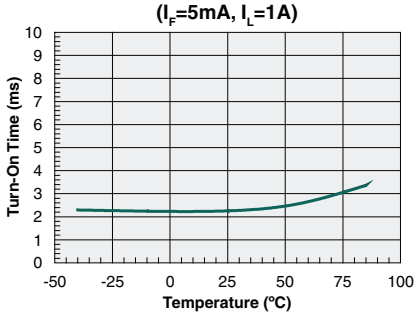
Typical Turn-Off Time vs. LED Forward Current (I_L=1A)



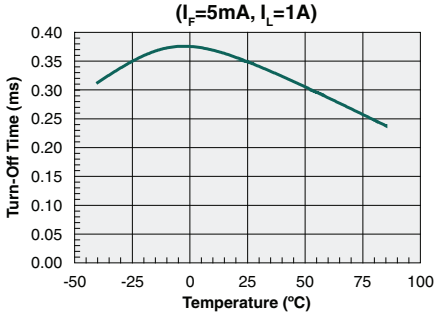
Typical On-Resistance vs. Temperature (I_F=10mA, I_L=1A)



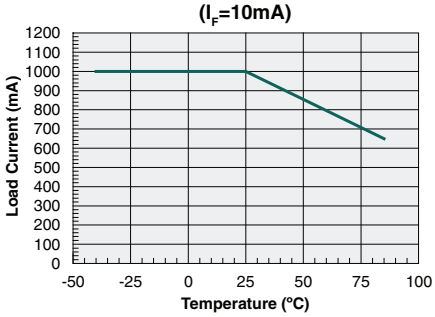
Typical Turn-On Time vs. Temperature (I_F=5mA, I_L=1A)



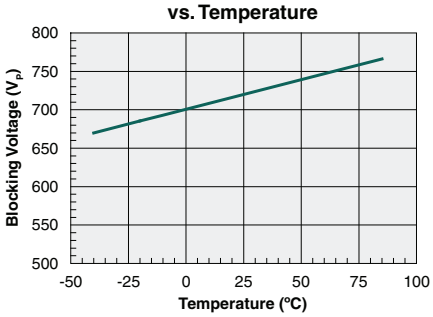
Typical Turn-Off Time vs. Temperature (I_F=5mA, I_L=1A)



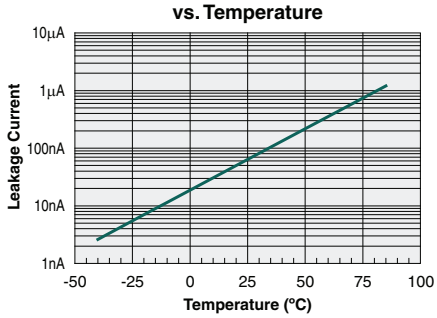
Maximum Load Current vs. Temperature (I_F=10mA)



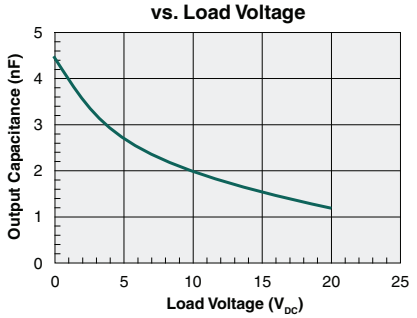
Typical Blocking Voltage vs. Temperature



Typical Leakage Current vs. Temperature



Typical Output Capacitance vs. Load Voltage



*The Performance data shown in the graphs above is typical of device operation. Unless otherwise noted, data is presented at 25°C.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

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Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1984Y	MSL 1

ESD Sensitivity

This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be (T_C - 5)ºC or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

Device	Classification Temperature (T_c)	Dwell Time (t_p)	Maximum Cycles
CPC1984Y	245ºC	30 seconds	1

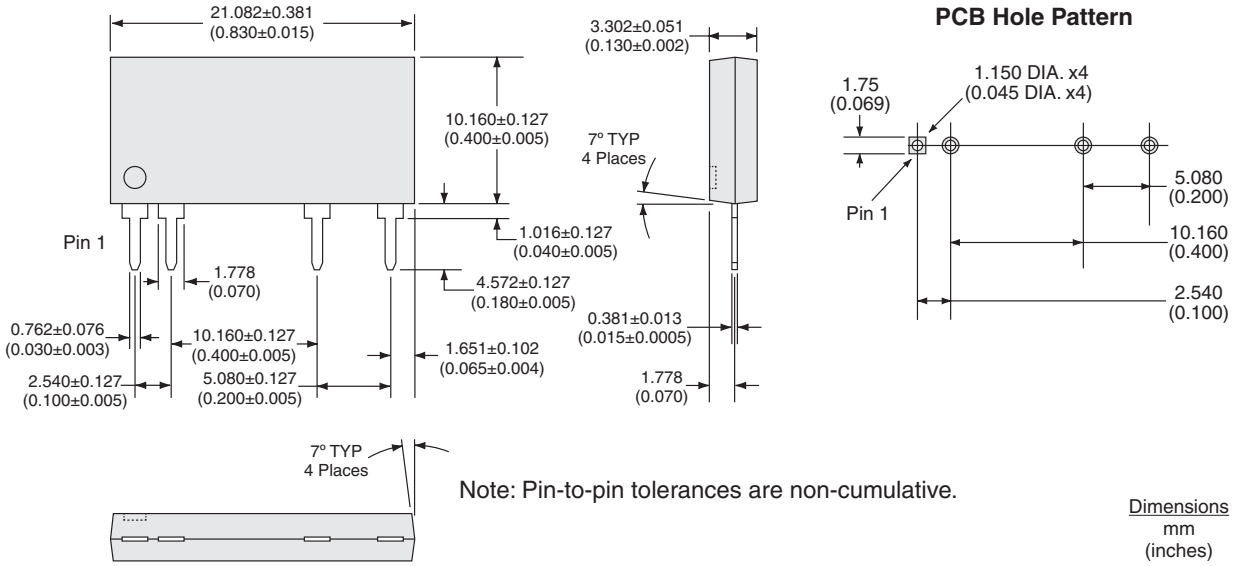
Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

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MECHANICAL DIMENSIONS

CPC1984Y Power SIP Package



Note: Pin-to-pin tolerances are non-cumulative.

Dimensions
mm
(inches)

For additional information please visit our website at: www.ixysic.com

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